



# Global Silicon Wafer Japan TC Chapter

## Meeting Summary and Minutes

Japan Standards-Spring Meetings 2023

Thursday, April 13, 2023, 10:00 –12:00[JST]

SEMI Japan Office/Official Virtual TC Chapter Meeting (Hybrid)

### TC Chapter Announcements

*Next TC Chapter Meeting*

Friday, August 25, 2023, 10:00-12:00 [JST]

SEMI Japan Office/Official Virtual TC Chapter Meeting (Hybrid)

### Table 1 Meeting Attendees

*Italics indicate virtual participants*

**Co-Chairs:** Name (Company) Tetsuya Nakai (SUMCO), Ryuji Takeda (Global Wafers Japan)

**SEMI Staff:** Mami Nakajo

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
<i>SELF</i>	<i>Kawai</i>	<i>Naoyuki</i>	SUMCO	Nakai	Tetsuya
<i>Wafer Information Service</i>	<i>Yoshise</i>	<i>Masanori</i>	<i>Shin-Etsu Handotai Co., Ltd.</i>	<i>Tsunoda</i>	<i>Hitoshi</i>
<i>Osaka Metropolitan University</i>	<i>Inoue</i>	<i>Naohisa</i>	<i>Kobelco Research Institute, Inc.</i>	<i>Tsunaki</i>	<i>Hedetoshi</i>
<i>Miraial Co., Ltd.</i>	<i>Nagashima</i>	<i>Tsuyoshi</i>	<i>Kobelco Research Institute, Inc.</i>	<i>Kannaka</i>	<i>Masato</i>
<i>Global Wafers Japan</i>	<i>Takeda</i>	<i>Ryuji</i>	SEMI Japan	Nakajo	Mami
<i>X-FAB Sarawak Sdn. Bhd</i>	<i>Liew</i>	<i>Emily</i>	SEMI Japan	Okayasu	Nobuko
Acteon NEXT LLC	Komatsu	Shoji			

### Table 2 Leadership Changes

<i>WG/TF/SC/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
None		

### Table 3 Committee Structure Changes

<i>Previous WG/TF/SC Name</i>	<i>New WG/TF/SC Name or Status Change</i>
JA Shipping Box TF	Disband

### Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
None		

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.



**Table 5 Activities Approved by the GCS between meetings of the TC Chapter**

#	Type	SC/TF/WG	Details
None			

No activity requested by the Japan TC Chapter between meetings.

**Table 6 Authorized Activities**

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	Type	SC/TF/WG	Details
None			

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

**Table 7 Authorized Ballots**

#	When	TF	Details
None			

**Table 8 SNARF(s) Granted a One-Year Extension**

#	TF	Title	Expiration Date
5772	Japan Test Method Task Force	Revision of MF391-0310: Test Methods for Minority Carrier Diffusion Length in Extrinsic Semiconductors by Measurement of Steady-state Surface photovoltage	2024/09/11
6687	Japan Test Method Task Force	Revision of M51: Test Method for Characterizing Silicon Wafer by Gate Oxide Integrity	2024/10/02

**Table 9 SNARF(s) Abolished**

#	TF	Title
None		

**Table 10 Standard(s) to receive Inactive Status**

Standard Designation	Title
SEMI M31-0718	Specification for Mechanical Features of Front-Opening Shipping Box Used to Transport and Ship 300 mm Wafers

**Table 11 New Action Items**

Item #	Assigned to	Details
20230413-01	SEMI Staff	To confirm details with SEMI NA Staff regarding the reapproval documents that the NA co-chair has requested to be transferred to Japan for authorization.

**Table 12 Previous Meeting Action Items**

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20221214-01	JA Shipping Box TF	To review SEMI M31-0718, Specification for Mechanical Features of Front-Opening Shipping Box Used to Transport and Ship 300 mm Wafers to confirm whether to Reapproval by the next TC chapter meeting. >Done

### 1 Welcome, Reminders, and Introductions

Tetsuya Nakai (SUMCO), called the meeting to order at 10:00. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

**Attachment:** 01-02\_Required Element Nov 2022\_E+J (new template)

### 2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

<b>Motion:</b>	Approve the minutes as written
<b>By / 2<sup>nd</sup>:</b>	Shoji Komatsu (Acteon NEXT LLC) / Naoyuki Kawai (Self)
<b>Discussion:</b>	None
<b>Vote:</b>	9 in favor and 0 opposed. <b>Motion Passed.</b>

**Attachment:** 02-01\_20221214\_Global Silicon Wafer Japan TC Chapter Meeting Minutes\_approved\_r1

### 3 Ballot Review

None

### 4 Subcommittee and Task Force Reports

#### 4.1 International Advanced Wafer Geometry Task Force

Masanori Yoshise (Wafer Information Service) reported for the International Advanced Wafer Geometry Task Force as attached.

**Attachment:** 04-01\_AWG NA Spring 2023 minutes got SWC Japan

#### 4.2 International/Japan Test Method Task Force

Ryuji Takeda (Global Wafers Japan) reported for the Japan Test Method Task Force as attached.

**Attachment:** 04-02\_Japan Test Method TF meeting minutes April 6 2023

#### 4.3 International Advanced Automated Surface Inspection Task Force

No special topic was reported at this meeting.

#### 4.4 International Polished Wafers Task Force

No special topic was reported at this meeting.

#### 4.5 International Epitaxial Wafers Task Force

No special topic was reported at this meeting.

#### 4.6 International Annealed Wafers Task Force

No special topic was reported at this meeting.

#### 4.7 International SOI Wafers Task Force

No special topic was reported at this meeting.

#### 4.8 International Terminology Task Force

No special topic was reported at this meeting.

#### 4.9 JA Shipping Box TF

Shoji Komatsu (Acteon NEXT LLC) submitted a motion to disband JA Shipping Box TF.

<b>Motion:</b>	Disband the TF of JA Shipping BOX
<b>By / 2<sup>nd</sup>:</b>	Shoji Komatsu (Acteon NEXT LLC) / Ryuji Takeda (Global Wafers Japan)
<b>Discussion:</b>	None
<b>Vote:</b>	5 in favor and 0 opposed. <b>Motion Passed.</b>

## 5 Liaison Reports

### 5.1 Silicon Wafer Europe TC Chapter

Mami Nakajo (SEMI) gave the Silicon Wafer Europe TC Chapter as attached..

**Attachment:** 05-01\_EU Si Wafer TC Chapter Liaison Report Dec 2022 v1

### 5.2 Silicon Wafer North America TC Chapter

Tetsuya Nakai (SUMCO) reported for the Silicon North America TC Chapter as attached.

**Attachment:** 05-02\_NA Si Wafer TC Chapter Liaison Report April 2023

### 5.3 GCS

No special topic was reported at this meeting.

## 6 SEMI Staff Report

Mami Nakajo (SEMI) gave the SEMI Staff Report.

**Attachment:** 06-01\_Staff Report March 2023 v3

## 7 Old Business

### 7.1 Project Period Review



7.1.1 #5772 SNARF for: Revision of MF391-0310: Test Methods for Minority Carrier Diffusion Length in Extrinsic Semiconductors by Measurement of Steady-state Surface photovoltage

Ryuji Takeda (Global Wafers Japan) requested to extend one year of the project period for the SNARF #5772.

<b>Motion:</b>	Approve a 1 year extension of the project period for the SNARF Document Number: 5772 SNARF for: Revision of MF391-0310: Test Methods for Minority Carrier Diffusion Length in Extrinsic Semiconductors by Measurement of Steady-state Surface photovoltage
<b>By / 2<sup>nd</sup>:</b>	Ryuji Takeda (Global Wafers Japan) / Naoyuki Kawai (Self)
<b>Discussion:</b>	None
<b>Vote:</b>	6 in favor and 0 opposed. <b>Motion Passed.</b>

7.1.2 #6887 SNARF for: Revision of M51: Test Method for Characterizing Silicon Wafer by Gate Oxide Integrity

Ryuji Takeda (Global Wafers Japan) requested to extend one year of the project period for the SNARF #6887.

<b>Motion:</b>	Approve a 1 year extension for the SNARF Document Number: 6687 SNARF for: Revision of M51: Test Method for Characterizing Silicon Wafer by Gate Oxide Integrity
<b>By / 2<sup>nd</sup>:</b>	Ryuji Takeda (Global Wafers Japan) / Naoyuki Kawai (Self)
<b>Discussion:</b>	Done
<b>Vote:</b>	6 in favor and 0 opposed. <b>Motion Passed.</b>

7.2 5 Year Review Check

7.2.1 SEMI M51-1012: Test Method for Characterizing Silicon Wafer by Gate Oxide Integrity

Ongoing

7.2.2 SEMI M60-1014: Test Method for Time Dependent Dielectric Breakdown Characteristics of SiO<sub>2</sub> Films for Si Wafer Evaluation

Ongoing

**8 New Business**

8.1 Proposal of New Activity

None

**9 Action Item Review**

9.1 Open Action Item

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20221214-01	JA Shipping Box TF	To review SEMI M31-0718, Specification for Mechanical Features of Front-Opening Shipping Box Used to Transport and Ship 300 mm Wafers to confirm whether to Reapproval by the next TC chapter meeting. >Done

9.2 New Action Item

**Action Item: 20230413-01 (SEMI Staff) :** To confirm details with SEMI NA Staff regarding the reapproval documents that the NA co-chair has requested to be transferred to Japan for authorization.



## 10 Next Meeting and Adjournment

The next meeting is scheduled for as follows.

Friday, August 25, 2023, 10:00am-noon(Hybrid)

Please check [www.semi.org/standards](http://www.semi.org/standards) for updates.

See <http://www.semi.org/standards-events> for the current list of events.

Adjournment: [11:53]>.

Respectfully submitted by:

Mami Nakajo

Coordinator

SEMI Japan

Phone: +81.3.3222.5757

Email: [mnakajo@semi.org](mailto:mnakajo@semi.org)

Minutes tentatively approved by:

Tetsuya Nakai (SUMCO), Co-chair	May 11, 2023
Ryuji Takeda (Global Wafers Japan), Co-chair	May 11, 2023

**Table 13 Index of Available Attachments#1**

<i>Title</i>	<i>Title</i>
01-02_Required Element Nov 2022_E+J (new template)	05-01_EU Si Wafer TC Chapter Liaison Report Dec 2022 v1
02-01_20221214_Global Silicon Wafer Japan TC Chapter Meeting Minutes_approved	05-02_NA Si Wafer TC Chapter Liaison Report April 2023
04-01_AWG NA Spring 2023 minutes got SWC Japan	06-01_Staff Report March 2023 v3
04-02_Japan Test Method TF meeting minutes April 6 2023	

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at [www.semi.org](http://www.semi.org). For additional information or to obtain individual attachments, please contact Mami Nakajo at the contact information above.